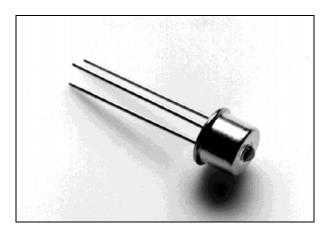




Data Sheet

September 2004



Features

- 860 nm Surface-Emitting LED
- 70 MHz Bandwidth
- Designed for 50/125 µm fiber

Applications

- LANs
- · Test Equipment
- · General Purpose

Ordering Information

MF194 TO-46 Package
MF194 ST ST Housing
MF194 SC SC Housing
MF194 SMA SMA Housing
MF194 FC FC Housing

-40°C to +85°C

Note: Rated Fiber coupled power apply only on the TO-46 package, for housing options fiber coupled power is typically 10% less.

Description

This device is designed for Ethernet and general applications and offers an excellent price/performance ratio for cost-effective solutions. Its double-lens optical system results in optimum coupling of power into the fiber.

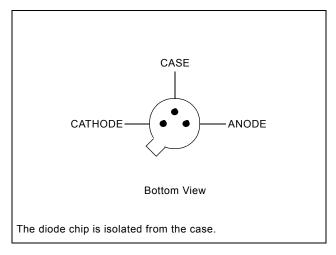


Figure 1 - Pin Diagram

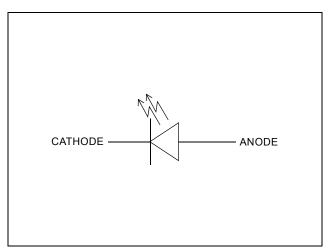


Figure 2 - Functional Schematic

Optical and Electrical Characteristics - Case Temperature 25°C

Parameter	Symbol	Min	Тур	Max	Unit	Test Condition	
Fiber-Coupled Power (Figures 3, 4, and 5) (Table 1)	P _{fiber}	25	45		μW	I _F =60 mA (Note 1)	Fiber: 50/125 μm
Rise and Fall Time (10-90%)	t _r ,t _f		5	7	ns	I _F =60 mA (no bias)	Graded Index
Bandwidth (3dB _{el})	f _c		70		MHz	I _F =60 mA	NA=0.20
Peak Wavelength	λ_{p}	840	860	880	nm	I _F =60mA	
Spectral Width (FWHM)	Δλ		50		nm	I _F =60 mA	
Forward Voltage (Figure 7)	V _F		1.7	1.9	V	I _F =60 mA	
Reverse Current	I _R			20	μΑ	V _R =1 V	
Capacitance	С		250		pF	V _R -0 V, f=1 MH	łz

Note 1: Measured at the exit of 100 meters of fiber.

Absolute Maximum Ratings

Parameter	Symbol	Limit	
Storage Temperature	T _{stg}	-55 to +125°C	
Operating Temperature (derating: Figure 6)	T _{op}	-40 to +85°C	
Electrical Power Dissipation (derating: Figure 6)	P _{tot}	160 mW	
Continuous Forward Current (f<10 kHz)	I _F	80 mA	
Peak Forward Current (duty cycle<50%,f>1 MHz	I _{FRM}	130 mA	
Reverse Voltage	V _R	1.5 V	
Soldering Temperature (2 mm from the case for 10 sec.)	T _{sld}	260°C	

Thermal Characteristics

Parameter	Symbol	Min.	Тур.	Max.	Unit
Thermal Resistance - Infinite Heat Sink	R _{thjc}			200	°C/W
Thermal Resistance - No Heat Sink	R _{thja}			500	°C/W
Temperature Coefficient - Optical Power	d <i>P</i> /d <i>T</i> _j		-0.5		%/°C
Temperature Coefficient - Wavelength	$\mathrm{d}\lambda/\mathrm{d}T_{\mathrm{j}}$		0.3		nm/°C

Typical Fiber-Coupled Power

Core Diameter/Cladding Diameter Numerical Aperture					
50/12 5μm 0.20	62.5/125 μm 0.275	100/140 μm 0.29	200/230 μm 0.37		
45 μW	95 μW	210 μW	440 μW		

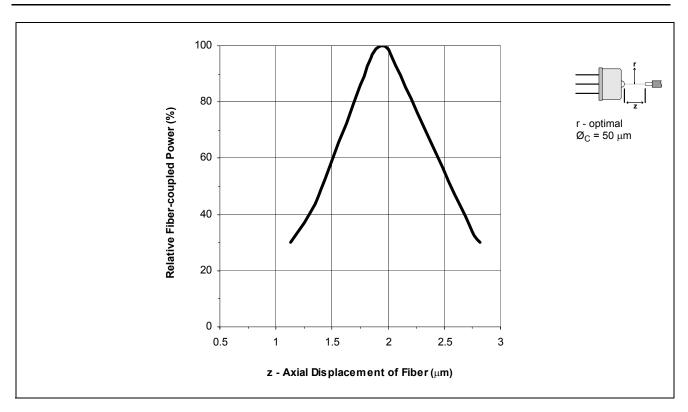


Figure 3 - Relative Fiber-coupled Power vs. z - Axial Displacement of Fiber

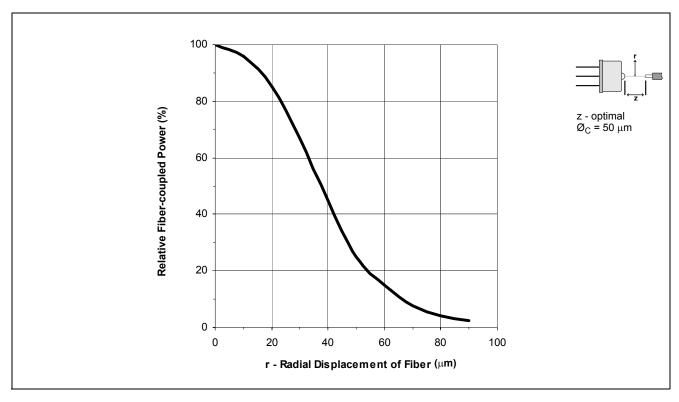


Figure 4 - Relative Fiber-coupled Power vs. r - Radial Displacement of Fiber

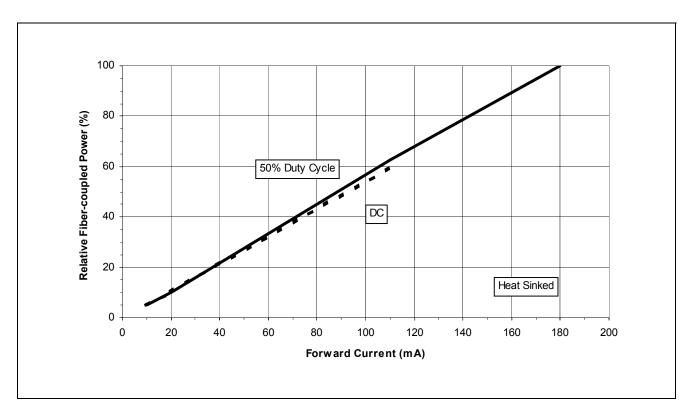


Figure 5 - Relative Fiber-coupled Power vs. Forward Current

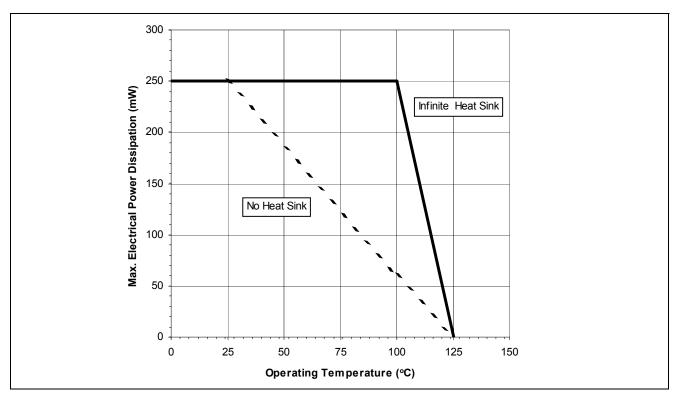


Figure 6 - Max. Electrical Power Dissipation vs. Operating Temperature

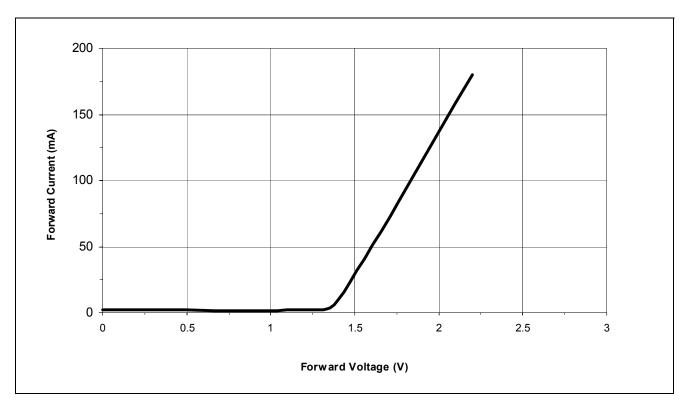
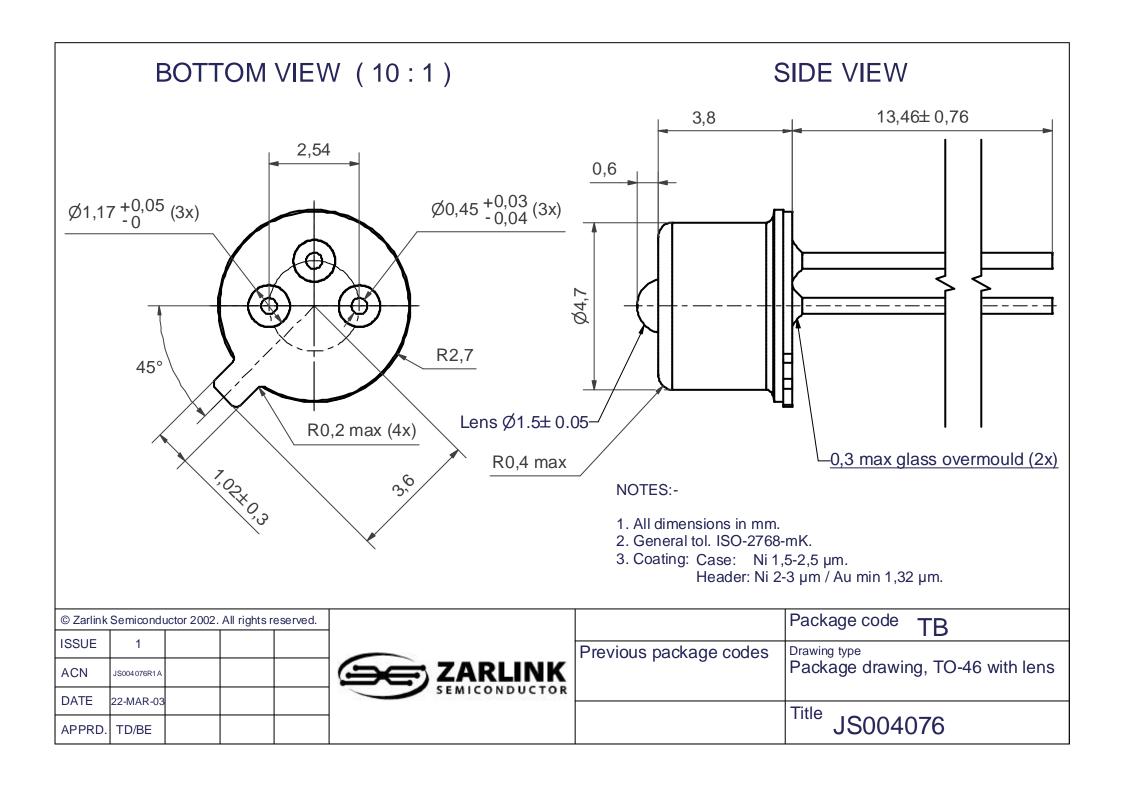


Figure 7 - Forward Current vs. Forward Voltage





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